



100% Material Declaration Data Sheet for 7 Series FG484 Package

PK684 (v1.0) Nov 21, 2014

Average Weight: 2.3524 g

Component	Substance Description	CAS Number or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.048674	2.069%
	Silicon	7440-21-3	100.00		0.048674	
Die Attach Material					0.008859	0.377%
	Silver	7440-22-4	77.50		0.006866	
	Bismaleimide monomer	Trade Secret	15.00		0.001329	
	Acrylate monomer	Trade Secret	7.50		0.000664	
Mold Compound					1.125465	47.844%
	Solid Epoxy Resin	Trade Secret	5.00		0.056273	
	Phenol Resin	Trade Secret	3.00		0.033764	
	Phenol Novolac	9003-35-4	3.00		0.033764	
	Metal Hydroxide	Trade Secret	3.00		0.033764	
	Carbon Black	1333-86-4	0.30		0.003376	
	Silica fused	60676-86-0	70.40		0.792327	
	Silicon Dioxide	7631-86-9	15.00		0.168820	
	Silica, crystalline	14808-60-7	0.30		0.003376	
Copper Wire					0.006997	0.297%
	Copper	7440-50-8	98.25		0.006875	
	Palladium	7440-05-3	1.75		0.000122	
Solder Ball					0.460670	19.583%
	Tin	7440-31-5	63.00		0.290222	
	Lead	7439-92-1	37.00		0.170448	
Substrate					0.701689	29.829%
	Gold (Au)	7440-57-5	1.99		0.013964	
	Nickel (Ni)	7440-02-0	6.09		0.042733	
	Copper Foil	7440-50-8	7.65		0.053679	
	Copper Plating	7440-50-8	37.77		0.265028	
	BT Core	Trade Secret	40.67		0.285377	
	Solder Mask	Trade Secret	5.83		0.040908	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
11/21/14	1.0	Initial Xilinx release.

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